### How2AppNote 018

# eGaN® TECHNOLOGY

# How to Design a 300 W 48 V to 12 V, 9 V, 5 V Digitally Controlled <sup>1</sup>/<sub>16</sub><sup>th</sup> Brick DC-DC Converter Using eGaN<sup>®</sup> FETs



## Introduction

Brick DC-DC converters are widely used in data center, telecommunication and automotive applications, converting a nominal 48 V to a nominal 12 V distribution bus among other output voltages.

The main trend has been towards higher power density given the form factor is fixed. This application note discusses the design of a digitally controlled 1/16<sup>th</sup> brick converter using GaN FETs for a 48 V to 12 V, 9 V, 5 V application, with up to 25 A output current, 300 W output power, a peak efficiency of 95.8%, and maximum power density of 730 W/in<sup>3</sup>.

The standard dimension of the 1/16<sup>th</sup> brick converter is 33 x 22.9 mm (1.3 x 0.9 inch). The height limit for this design is set to 10 mm (0.4 inch).

#### **Design challenges**

The key challenge for a high-power-density  $1/16^{th}$  brick is magnetics. Due to space and dimension constraints, the magnetics are limited in size and shape. In addition, high output current (up to 25 A) requires high saturation current rating, but inductors with high saturation current are usually bulky. A two-phase synchronous buck topology can be used so that two inductors share the output current and therefore the peak current requirement can be reduced. The simplified schematic is shown in figure 1.

The second challenge lies in the selection of the switching transistors. They need to have a very good hard switching figure-of-merit [2], and come in a small footprint, since the magnetics occupy a significant amount of board space. For these reasons, GaN FETs in chip scale packages are selected in this design.

The next challenge is the lack of GaN-compatible controllers. Off-theshelf MOSFET controllers usually have long dead times (> 20 ns), slow and damped gate drivers, and are unable to handle negative voltages of -2 to -3 V at the switch node. As a result, circuit adaptations of MOSFET controllers are required to ensure proper operation that come at the expense of efficiency. In this design, a dsPIC33 microcontroller, from Microchip, is used to fully exploit the high performance of GaN FETs.

## Power stage design

The synchronous buck converter is selected as the base topology for this design. Considering the maximum output current of 25 A, if a single inductor is used, its current rating needs to be at least 33 A, assuming 30% peak-to-average current ripple. Inductors that satisfy this requirement will not fit under the height limit. If a two-phase synchronous buck converter is used instead, each inductor only conducts 12.5 A DC current. With 30% ripple, the peak current is 16.25 A.

**EPC2053** GaN FETs, with 3.2 m $\Omega$  R<sub>DS(on)</sub> are used in order to reduce the converter size and conduction loss. Discrete GaN-specific gate drivers,

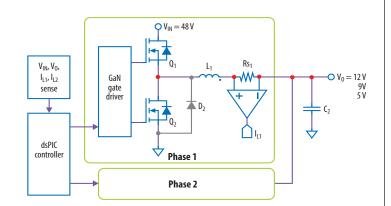


Figure 1. Simplified schematic diagram of the 1/16<sup>th</sup> brick converter

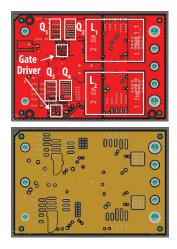


Figure 2. First two layers of the printed circuit board showing symmetric two-phase layout

uP1966A from  $\mu$ Pl semiconductor, are also selected. This eliminates the need for anti-parallel diode (D<sub>2</sub> in figure 1) and reduces loss.

To take advantage of the fast switching of GaN FETs, the power loop inductance needs to be minimized. Using the optimum layout [1,2] technique, the second layer of the printed circuit board (PCB) is a ground plane, as shown in figure 2. Another two layers of ground plane are also included in this six-layer PCB, for better heat sinking.

For inductors the TDK B82559 series [3] are good options, with a dimension of 13 x 10.7 mm (0.51 x 0.42 inch), and a height of 5 mm or 6 mm. They also have high saturation current rating and low DCR. The 2.4  $\mu$ H inductor has a saturation current rating of 16.5 A. Therefore, 500 kHz switching frequency is selected for the design, resulting in 16.25 A peak current under nominal operating condition that satisfies the saturation current requirement.

#### **Digital control**

A **dsPIC33CK** digital controller from Microchip [4] is used to address the controller compatibility issue. It is a 16-bit processor with a maximum CPU speed of 100 MIPS. The pulse-width modulation (PWM) module can be configured in high-resolution mode, resulting in 0.25 ns resolution in duty cycle and dead times, allowing accurate adjustment of dead times to fully exploit the high performance of GaN FETs.

There are two options for the digital control loop: a) single-voltage loop with current balancing; or b) multi-loop controller. Both options require current sensing circuitry, consisting of sense resistors and differential amplifiers. The multi-loop controller is selected for this design. In addition, 1 m $\Omega$  sense resistors and low-noise amplifiers, MCP6C02, are used. The control block diagram is shown in figure 3. The same current reference I<sub>REF</sub> is used for the two independent current loops. As a result, the current in both inductors will be regulated to the same value. The bandwidth of the two inner current loops are set to 10 kHz, and the outer voltage loop bandwidth is set to 2 kHz.

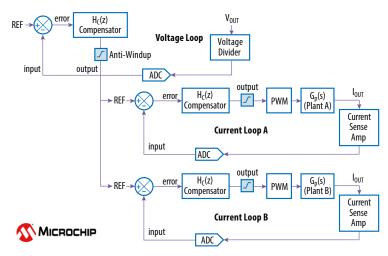


Figure 3. Control block diagram of the multi-loop 2-phase converter

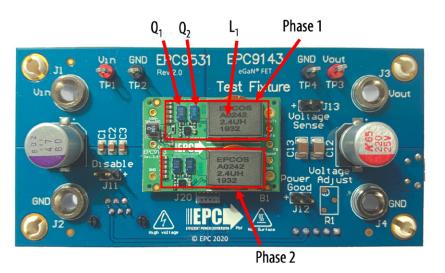


Figure 4. <sup>1</sup>/<sub>16</sub><sup>th</sup> brick converter EPC9143 mounted on the EPC9531 test fixture

#### **Design validation setup**

Figure 4 shows a photo of the 1/16<sup>th</sup> brick converter (EPC9143) mounted on the EPC9531 test fixture. The power stage components (gate drivers, GaN FETs and inductors) are on the top side, and control components (current sense amplifiers, digital controller) are on the bottom side, shown in figure 5.

The total stand-off height of the design is 9.1 mm, including 6 mm from the inductors, 1.6 mm from the PCB thickness, and 1.5 mm for the bottom component (0805 size capacitors).

The EPC9531 test fixture has additional input capacitance of 47  $\mu F$  and additional output capacitance of 200  $\mu F$ . These extra capacitances help maintain controller stability. The fixture also provides programming ports and USB communication.

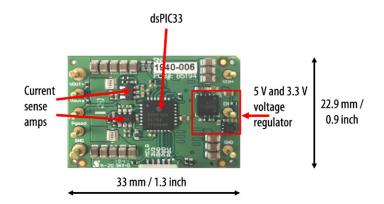


Figure 5. Bottom side of the 1/16<sup>th</sup> brick converter

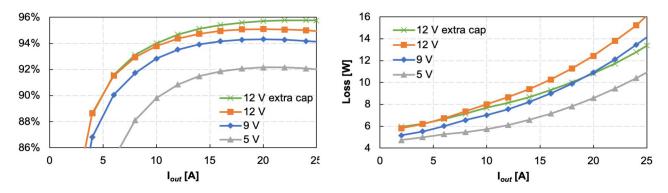


Figure 6. Measured efficiency and loss for the 1/16<sup>th</sup> brick converter

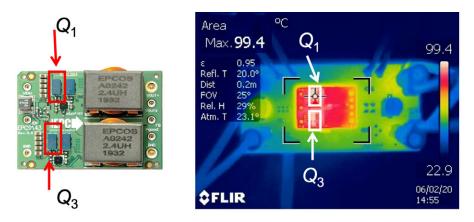


Figure 7. Thermal image of the 1/16<sup>th</sup> brick converter operating in thermal steady state.  $V_{IN}$  = 48 V,  $V_{OUT}$  = 12 V, 25 A output current, airflow 800 LFM

### **Design results**

With 800 LFM airflow, the measured thermal steady state efficiency and loss are shown in figure 6, for a range of output current up to 25 A with different output voltages: 5 V, 9 V, and 12 V. The peak efficiency is 95% when the current is from 20 A to 25 A at 12 V output. The maximum device temperature reached 100°C, as illustrated in the thermal image in figure 7.

Due to space limitation, the brick converter can only fit a total of 8.2 µF input capacitance. When an additional 2  $\mu F$  capacitance is added, the peak efficiency is improved to 95.8%, and the loss is reduced by 2.7 W (15%).

# Conclusion

This application note evaluated the design challenges of a high power <sup>1</sup>/<sub>16</sub><sup>th</sup> brick converter and showed that using eGaN FETs could increase maximum load current over state-of-art MOSFET designs. A 300 W, 48 V to 12 V maximum output, 300 W converter design with output

current capability up to 25 A was tested with peak efficiency of the converter reaching 95%. With 2  $\mu$ F extra input capacitance, the peak efficiency can reach 95.8%.

#### References

[1] A. Lidow, M. De Rooij, J. Strydom, D. Reusch, and J. Glaser, GaN transistors for efficient power conversion, 3rd ed. John Wiley & Sons, 2019. ISBN: 978-1119594147.

[2] D. Reusch and J. Glaser, "DC-DC Converter Handbook - A Supplement to GaN Transistors for Efficient Power Conversion," 1st ed. Power Conversion Publications, 2015, ISBN 978-0-9966492-0-9.

[3] TDK. (2012). SMT power inductors, [Online]. Available: https://www. tdk-electronics.tdk.com/inf/30/db/ind\_2008/b82559\_a013.pdf.

[4] Microchip Technology Inc. (2019). 16-bit PIC Microcontrollers Family, [Online]. Available: https://www.microchip.com/designcenters/16-bit.



